

#4/B  
9-25-00  
Robert

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Po-Yao Lin et al.

Serial No.: 09/379,599

Filed: August 24, 1999

For: Integrated Circuit Package with  
Multiple Heat Dissipation Paths

Art Unit:

Examiner: Chervinnsky

Atty Docket: 0694/00063

SUPPLEMENTAL PRELIMINARY AMENDMENTVIA FAX NO. 703-305-3431Commissioner for Patents  
Washington, D.C. 20231

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SEP 21 2000

TECHNOLOGY CENTER 2800

Sir:

Prior to initial examination, please amend the above-captioned case as follows.

IN THE SPECIFICATION:

Page 7, line 8 delete "(not shown)" and insert --- 140 ---.

REMARKS

Claims 1, 3, <sup>4</sup> and 8-12 are now in the application. The recent telephone conference with the Examiner is hereby noted with appreciation. As discussed, figure 1 has been amended to include the additional heat sink disclosed at page 7, line 8 of the specification and the specification has been amended accordingly. None of these amendments is believed to involve any new matter. Accordingly, it is respectfully

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